

PCN Number:	20190430001.1		PCN Date:	May 1, 2019	
Title:	Qualification of FFAB as an additional Fab site option for select BICMOS13 devices				
Customer Contact:	PCN Manager		Dept:	Quality Services	
Proposed 1st Ship Date:	Jul 31, 2019	Estimated Sample Availability:	Date provided at sample request.		
Change Type:					
<input type="checkbox"/>	Assembly Site	<input type="checkbox"/>	Assembly Process	<input type="checkbox"/>	Assembly Materials
<input type="checkbox"/>	Design	<input type="checkbox"/>	Electrical Specification	<input type="checkbox"/>	Mechanical Specification
<input type="checkbox"/>	Test Site	<input type="checkbox"/>	Packing/Shipping/Labeling	<input type="checkbox"/>	Test Process
<input type="checkbox"/>	Wafer Bump Site	<input type="checkbox"/>	Wafer Bump Material	<input type="checkbox"/>	Wafer Bump Process
<input checked="" type="checkbox"/>	Wafer Fab Site	<input type="checkbox"/>	Wafer Fab Materials	<input type="checkbox"/>	Wafer Fab Process
		<input type="checkbox"/>	Part number change		

PCN Details

Description of Change:

Texas Instruments is pleased to announce the qualification of its FFAB fabrication facility as an additional Wafer Fab source for the selected devices listed in the "Product Affected" section.

Current Sites			Additional Sites		
Current Fab Site	Process	Wafer Diameter	Additional Fab Site	Process	Wafer Diameter
MAINEFAB	BICMOS13	200 mm	FFAB	BICMOS13	200mm

Qual details are provided in the Qual Data Section.

Reason for Change:

Continuity of Supply

Anticipated impact on Form, Fit, Function, Quality or Reliability (positive / negative):

None

Changes to product identification resulting from this PCN:

Current

Chip Site	Chip Site Origin (20L)	Chip Site Country Code (21L)	Chip Site City
MAINEFAB	CUA	USA	South Portland

New Fab Site

Chip Site	Chip Site Origin (20L)	Chip Site Country Code (21L)	Chip Site City
FR-BIP-1	TID	DEU	Freising

Sample product shipping label (not actual product label)



MADE IN: Malaysia
2DC: 20:

MSL 2 / 260C / 1 YEAR	SEAL DT
MSL 1 / 235C / UNLIM	03/29/04

OPT:
ITEM: 39
LBL: 5A (L)T0:1750





(1P) SN74LS07NSR
(Q) 2000 (D) 0336
(31T) LOT: 3959047MLA
(4W) TKY (1T) 7523483S12
(P)
(2P) REV: (V) 0033317
(20L) CS0: SHE (21L) CCO: USA
(22L) AS0: MLA (23L) ACO: MYS

Product Affected Group:

DS100MB203SQ/NOPB	DS100MB203SQE/NOPB	DS125MB203SQ/NOPB	DS125MB203SQE/NOPB
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Qualification Report

Approved 24-April-2019

Qualification Results

Data Displayed as: Number of lots / Total sample size / Total failed

Type	Test Name / Condition	Duration	Qual Device: DS100MB203SQ DS125MB203SQ	QBS Product Reference DS8100BR400SQ	QBS Product References: DS100MB203S DS125MB203A	QBS Product Reference DS90UR906Q SQ	QBS Product Reference DS90UH926QET65
HAST	Biased HAST, 130C/85%RH	96 Hours	-	-	-	1/77/0	3/231/0
AC	Autoclave 121C	96 Hours	-	0/135	-	3/231/0	3/231/0
TC	Temperature Cycle, - 65/150C	500 Cycles	-	0/230	-	3/231/0	3/231/0
HTSL	High Temp Storage Bake 150C	1000 Hours	-	0/154	-	1/45/0	1/45/0
HTOL	Life Test, 125C	1000 Hours	-	3/231/0	2/77/0	-	3/231/0
ELFR	Early Life Failure Rate, 125C	48 Hours	-	3/1839/0	-	1/800/0	3/2400/0
WBS	Bond Shear (Cpk>1.67)	Wires	-	-	-	-	1/30/0
WBP	Bond Pull (Cpk>1.67)	Wires	-	-	-	-	1/30/0
SD	Surface Mount Solderability >95% Lead Coverage	Pb Free	-	-	-	-	1/15/0
PD	Physical Dimensions	Per Package Drawing	-	-	-	-	3/30/0
HBM	ESD - HBM	2000 V	-	1/30/0	1/6/0	-	1/3/0
CDM	ESD - CDM	1000 V	-	1/30/0	1/3/0	-	1/3/0

Type	Test Name / Condition	Duration	Qual Device: DS100MB203SQ DS125MB203SQ	QBS Product Reference DS8100BR400SQ	QBS Product References: DS100MB203S DS125MB203A	QBS Product Reference DS90UR906Q SQ	QBS Product Reference DS90UH926QET65
LU	Latch-up	(per JESD78)	-	1/15/0	1/6/0	-	1/6/0
ED	Electrical Characterization	Per data sheet Parameters	Pass	1/30/0	1/30/0	-	3/90/0

- QBS: Qual By Similarity

- Qual Device DS90UH926QET65 is qualified at LEVEL3-260CG

A1 (PC): Preconditioning:

Performed for THB, Biased HAST, AC, uHAST & TC samples, as applicable

Ambient Operating Temperature by Automotive Grade Level:

Grade 0 (or E): -40°C to +150°C

Grade 1 (or Q): -40°C to +125°C

Grade 2 (or T): -40°C to +105°C

Grade 3 (or I): -40°C to +85°C

E1 (TEST): Electrical test temperatures of Qual samples (High temperature according to Grade level):

Room/Hot/Cold: HTOL, ED

Room/Hot: THB/HAST, TC/ PTC, HTSL, ELFR, ESD & LU

Room: AC/uHAST

Green/Pb-free Status:

Qualified Pb-Free (SMT) and Green

For questions regarding this notice, e-mails can be sent to the regional contacts shown below, or you can contact your local Field Sales Representative.

Location	E-Mail
USA	PCNAmericasContact@list.ti.com
Europe	PCNEuropeContact@list.ti.com
Asia Pacific	PCNAsiaContact@list.ti.com
WW PCN Team	PCN_ww_admin_team@list.ti.com

